Dual low-ohmic single-pole double-throw analog switchRev. 04 — 24 March 2010Product data sheet

1. General description

The NX3L4684 provides two low-ohmic single-pole double-throw analog switches, suitable for use as an analog or digital multiplexer/demultiplexer. It has a digital select input (nS) with Schmitt trigger action, two independent inputs/outputs (nY0, nY1) and a common input/output (nZ). Schmitt trigger action at the select input (nS) makes the circuit tolerant to slower input rise and fall times across the entire V_{CC} range from 1.4 V to 4.3 V.

A low input voltage threshold allows pin nS to be driven by lower level logic signals without a significant increase in supply current I_{CC} . This makes it possible for the NX3L4684 to switch 4.3 V signals with a 1.8 V digital controller, eliminating the need for logic level translation.

The NX3L4684 allows signals with amplitude up to V_{CC} to be transmitted from nZ to nY0 or nY1; or from nY0 or nY1 to nZ. Its low ON resistance (0.3 Ω for Y0 port, 0.5 Ω for Y1 port) and flatness (0.1 Ω) ensures minimal attenuation and distortion of transmitted signals.

2. Features

- Wide supply voltage range from 1.4 V to 4.3 V
- Very low ON resistance (peak) for Y0 port:
 - 0.8 Ω (typical) at V_{CC} = 1.4 V
 - 0.5 Ω (typical) at V_{CC} = 1.65 V
 - 0.3 Ω (typical) at V_{CC} = 2.3 V
 - 0.25 Ω (typical) at V_{CC} = 2.7 V
 - 0.25 Ω (typical) at V_{CC} = 4.3 V
- Break-before-make switching
- High noise immunity
- ESD protection:
 - HBM JESD22-A114F Class 3A exceeds 4000 V
 - MM JESD22-A115-A exceeds 200 V
 - CDM AEC-Q100-011 revision B exceeds 1000 V
- CMOS low-power consumption
- Latch-up performance exceeds 100 mA per JESD 78B Class II Level A
- 1.8 V control logic at V_{CC} = 3.6 V
- Control input accepts voltages above supply voltage
- Very low supply current, even when input is below V_{CC}
- High current handling capability (350 mA continuous current under 3.3 V supply)
- Specified from –40 °C to +85 °C and from –40 °C to +125 °C



3. Applications

- Cell phone
- PDA
- Portable media player

4. Ordering information

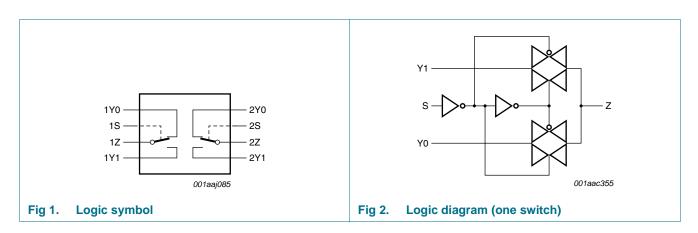
Table 1.Ordering information

Type number	Package							
	Temperature range	Name	Description	Version				
NX3L4684GM	–40 °C to +125 °C	XQFN10U	plastic extremely thin quad flat package; no leads; 10 terminals; UTLP based; body $2 \times 1.55 \times 0.5$ mm	SOT1049-2				
NX3L4684TK	–40 °C to +125 °C	HVSON10	plastic thermal enhanced very thin small outline package; no leads; 10 terminals; $3 \times 3 \times 0.85$ mm	SOT650-1				

5. Marking

Table 2. Marking	
Type number	Marking code
NX3L4684GM	D84
NX3L4684TK	D84

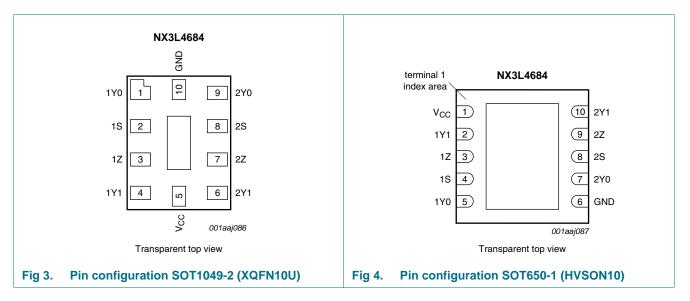
6. Functional diagram



Dual low-ohmic single-pole double-throw analog switch

7. Pinning information

7.1 Pinning



7.2 Pin description

Table 3. Pin des	cription		
Symbol	Pin		Description
	SOT1049-2	SOT650-1	
1Y0	1	5	independent input or output
1S	2	4	select input
1Z	3	3	common output or input
1Y1	4	2	independent input or output
V _{CC}	5	1	supply voltage
2Y1	6	10	independent input or output
2Z	7	9	common output or input
2S	8	8	select input
2Y0	9	7	independent input or output
GND	10	6	ground (0 V)

8. Functional description

Table 4.Function table^[1]

Input nS	Channel on
L	nY0
Н	nY1

[1] H = HIGH voltage level;

L = LOW voltage level.

9. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+4.6	V
VI	input voltage	select input nS	<u>[1]</u> –0.5	+4.6	V
V _{SW}	switch voltage	switch input nY0 or nY1	[2] _0.5	V _{CC} + 0.5	V
I _{IK}	input clamping current	$V_{I} < -0.5 V$	-50	-	mA
I _{SK}	switch clamping current	$V_{\rm I}$ < -0.5 V or $V_{\rm I}$ > $V_{\rm CC}$ + 0.5 V	-	±50	mA
I _{SW}	switch current	V_{SW} > -0.5 V or V_{SW} < V_{CC} + 0.5 V; source or sink current	-	±350	mA
		V _{SW} > –0.5 V or V _{SW} < V _{CC} + 0.5 V; pulsed at 1 ms duration, < 10 % duty cycle; peak current	-	±500	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	$T_{amb} = -40 \text{ °C to } +125 \text{ °C}$	[3] _	250	mW

[1] The minimum input voltage rating may be exceeded if the input current rating is observed.

[2] The minimum and maximum switch voltage ratings may be exceeded if the switch clamping current rating is observed but may not exceed 4.6 V.

[3] For XQFN10U packages: above 132 °C the value of P_{tot} derates linearly with 14.1 mW/K. For HVSON10 packages: above 135 °C °C the value of P_{tot} derates linearly with 17.2 mW/K.

10. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		1.4	4.3	V
VI	input voltage	select input nS	0	4.3	V
V _{SW}	switch voltage	switch input nY0 or nY1	<u>[1]</u> 0	V _{CC}	V
T _{amb}	ambient temperature		-40	+125	°C
$\Delta t / \Delta V$	input transition rise and fall rate	$V_{CC} = 1.4 \text{ V to } 4.3 \text{ V}$	[2] _	200	ns/V

[1] To avoid sinking GND current from terminal nZ when switch current flows in terminal nYn, the voltage drop across the bidirectional switch must not exceed 0.4 V. If the switch current flows into terminal nZ, no GND current will flow from terminal nYn. In this case, there is no limit for the voltage drop across the switch.

[2] Applies to select input nS signal levels.

11. Static characteristics

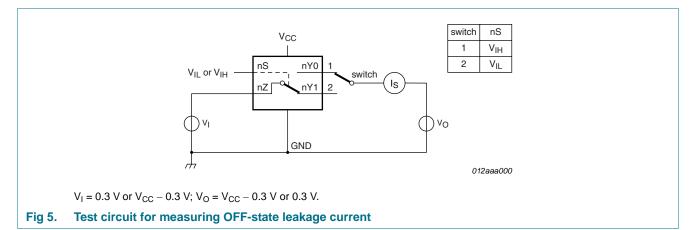
Table 7. Static characteristics

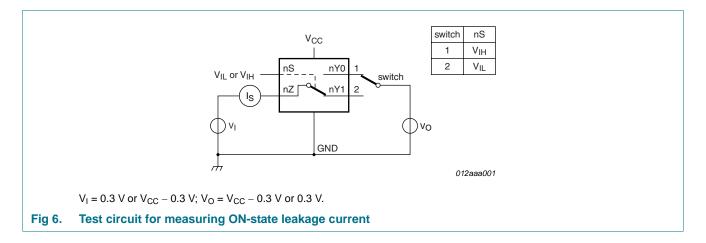
At recommended operating conditions; voltages are referenced to GND (ground 0 V).

Symbol	Parameter	Conditions	Ta	_{mb} = 25	°C	T _{amb} =	Unit		
			Min	Тур	Max	Min	Max (85 °C)	Max (125 °C)	
VIH	HIGH-level	$V_{CC} = 1.4 \text{ V} \text{ to } 1.6 \text{ V}$	0.9	-	-	0.9	-	-	V
	input voltage	V_{CC} = 1.65 V to 1.95 V	0.9	-	-	0.9	-	-	V
		V_{CC} = 2.3 V to 2.7 V	1.1	-	-	1.1	-	-	V
		V_{CC} = 2.7 V to 3.6 V	1.3	-	-	1.3	-	-	V
		$V_{CC} = 3.6 \text{ V to } 4.3 \text{ V}$	1.4	-	-	1.4	-	-	V
V _{IL}	LOW-level	$V_{CC} = 1.4 \text{ V} \text{ to } 1.6 \text{ V}$	-	-	0.3	-	0.3	0.3	V
	input voltage	$V_{CC} = 1.65 \text{ V} \text{ to } 1.95 \text{ V}$	-	-	0.4	-	0.4	0.3	V
		V_{CC} = 2.3 V to 2.7 V	-	-	0.5	-	0.5	0.4	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	-	-	0.5	-	0.5	0.5	V
		$V_{CC} = 3.6 \text{ V to } 4.3 \text{ V}$	-	-	0.6	-	0.6	0.6	V
I	input leakage current	select input nS; V ₁ = GND to 4.3 V; V _{CC} = 1.4 V to 4.3 V	-	-	-	-	±0.5	±1	μΑ
I _{S(OFF)}	OFF-state	nYn port; see <u>Figure 5</u>							
	leakage current	V_{CC} = 1.4 V to 3.6 V	-	-	±5	-	±10	±100	nA
		$V_{CC} = 3.6 V \text{ to } 4.3 V$	-	-	±10	-	±50	±200	nA
I _{S(ON)}	ON-state	nZ port; see <u>Figure 6</u>							
	leakage	V_{CC} = 1.4 V to 3.6 V	-	-	±5	-	±20	±200	nA
	current	$V_{CC} = 3.6 V \text{ to } 4.3 V$	-	-	±10	-	±50	±400	nA
I _{CC}	supply current	$V_I = V_{CC} \text{ or GND};$ $V_{SW} = GND \text{ or } V_{CC}$							
		$V_{CC} = 3.6 V$	-	-	100	-	300	3000	nA
		$V_{CC} = 4.3 V$	-	-	150	-	500	5000	nA
ΔI _{CC}	additional	V_{SW} = GND or V_{CC}							
	supply current	$V_{I} = 2.6 \text{ V}; V_{CC} = 4.3 \text{ V}$	-	2.0	4.0	-	7	7	μΑ
		$V_{I} = 2.6 \text{ V}; V_{CC} = 3.6 \text{ V}$	-	0.35	0.7	-	1	1	μΑ
		$V_{I} = 1.8 \text{ V}; V_{CC} = 4.3 \text{ V}$	-	7.0	10.0	-	15	15	μΑ
		$V_{I} = 1.8 \text{ V}; V_{CC} = 3.6 \text{ V}$	-	2.5	4.0	-	5	5	μΑ
		$V_{I} = 1.8 \text{ V}; V_{CC} = 2.5 \text{ V}$	-	50	200	-	300	500	nA
CI	input capacitance		-	1.0	-	-	-	-	pF
C _{S(OFF)}	OFF-state	port nY0	-	65	-	-	-	-	pF
	capacitance	port nY1	-	35	-	-	-	-	pF
C _{S(ON)}	ON-state	port nY0	-	260	-	-	-	-	pF
capacitance	port nY1	-	160	-	-	-	-	pF	

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11.1 Test circuits





11.2 ON resistance

Table 8. ON resistance

At recommended operating conditions; voltages are referenced to GND (ground = 0 V); for graphs see Figure 9 to Figure 21.

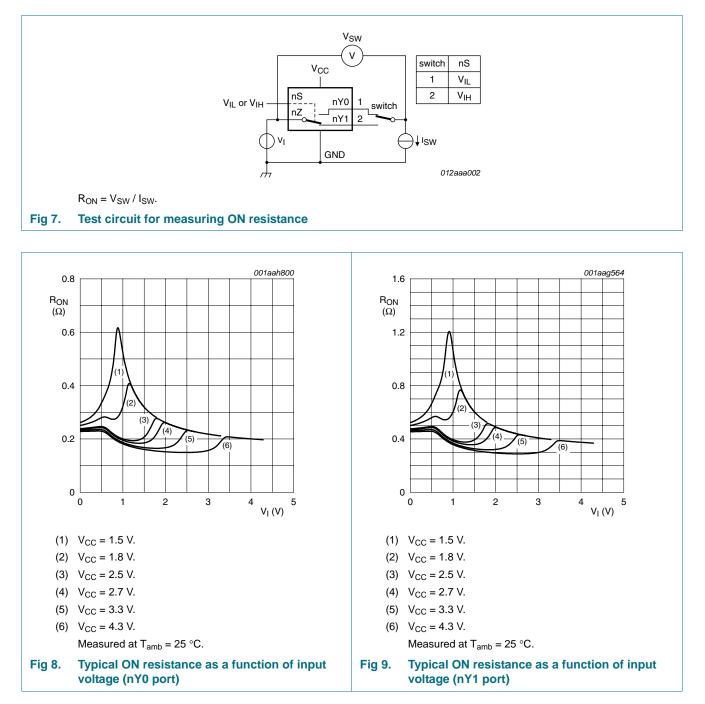
Symbol	Parameter	Conditions		-40	°C to +8	85 °C	–40 °C to	Unit	
				Min	Typ <mark>[1]</mark>	Max	Min	Max	
R _{ON(peak)}	ON resistance (peak)	port nY0; see Figure 7; $V_I = GND$ to V_{CC} ; $I_{SW} = 100$ mA							•
		$V_{CC} = 1.4 V$		-	0.85	2.0	-	2.2	Ω
		V _{CC} = 1.65 V		-	0.55	0.8	-	0.9	Ω
		$V_{CC} = 2.3 V$		-	0.35	0.5	-	0.6	Ω
		$V_{CC} = 2.7 V$		-	0.30	0.45	-	0.5	Ω
		$V_{CC} = 4.3 V$		-	0.30	0.45	-	0.5	Ω
		port nY1; see Figure 7; $V_I = GND$ to V_{CC} ; $I_{SW} = 100$ mA							
		$V_{CC} = 1.4 V$		-	1.65	3.7	-	4.1	Ω
		V _{CC} = 1.65 V		-	0.95	1.6	-	1.7	Ω
		$V_{CC} = 2.3 V$		-	0.55	0.8	-	0.9	Ω
		$V_{CC} = 2.7 V$		-	0.50	0.75	-	0.9	Ω
		$V_{CC} = 4.3 V$		-	0.50	0.75	-	0.9	Ω
ΔR_{ON}	ON resistance	$V_I = GND$ to V_{CC} ; $I_{SW} = 100 \text{ mA}$	[2]						
	mismatch between channels	$V_{CC} = 1.4 V$		-	0.15	0.3	-	0.3	Ω
	Charmers	V _{CC} = 1.65 V		-	0.15	0.2	-	0.3	Ω
		$V_{CC} = 2.3 V$		-	0.04	0.08	-	0.1	Ω
		$V_{CC} = 2.7 V$		-	0.04	0.075	-	0.1	Ω
		$V_{CC} = 4.3 V$		-	0.04	0.075	-	0.1	Ω
R _{ON(flat)}	ON resistance (flatness)	port nY0; $V_I = GND$ to V_{CC} ; $I_{SW} = 100 \text{ mA}$	<u>[3]</u>						
		$V_{CC} = 1.4 V$		-	0.5	1.7	-	1.8	Ω
		V _{CC} = 1.65 V		-	0.25	0.6	-	0.7	Ω
		$V_{CC} = 2.3 V$		-	0.1	0.2	-	0.2	Ω
		$V_{CC} = 2.7 V$		-	0.1	0.15	-	0.2	Ω
		$V_{CC} = 4.3 V$		-	0.1	0.20	-	0.25	Ω
		port nY1; $V_I = GND$ to V_{CC} ; $I_{SW} = 100 \text{ mA}$	<u>[3]</u>						
		$V_{CC} = 1.4 V$		-	1.0	3.3	-	3.6	Ω
		V _{CC} = 1.65 V		-	0.5	1.2	-	1.3	Ω
		$V_{CC} = 2.3 V$		-	0.15	0.3	-	0.35	Ω
		$V_{CC} = 2.7 V$		-	0.13	0.3	-	0.35	Ω
		$V_{CC} = 4.3 V$		-	0.2	0.4	-	0.45	Ω

[1] Typical values are measured at $T_{amb} = 25 \ ^{\circ}C$.

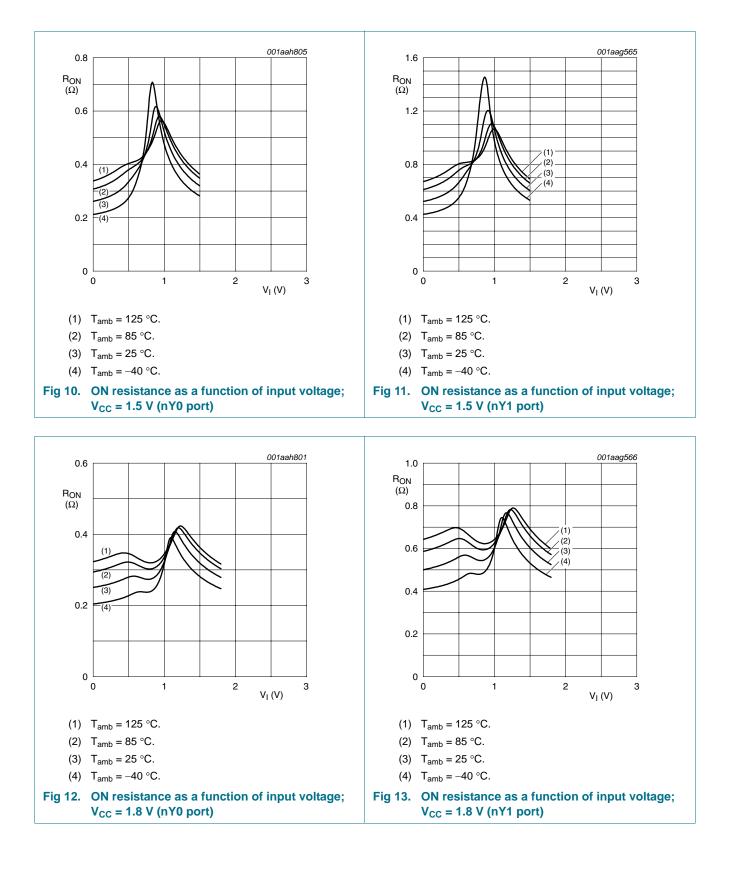
[2] Measured at identical V_{CC} , temperature and input voltage.

[3] Flatness is defined as the difference between the maximum and minimum value of ON resistance measured at identical V_{CC} and temperature.

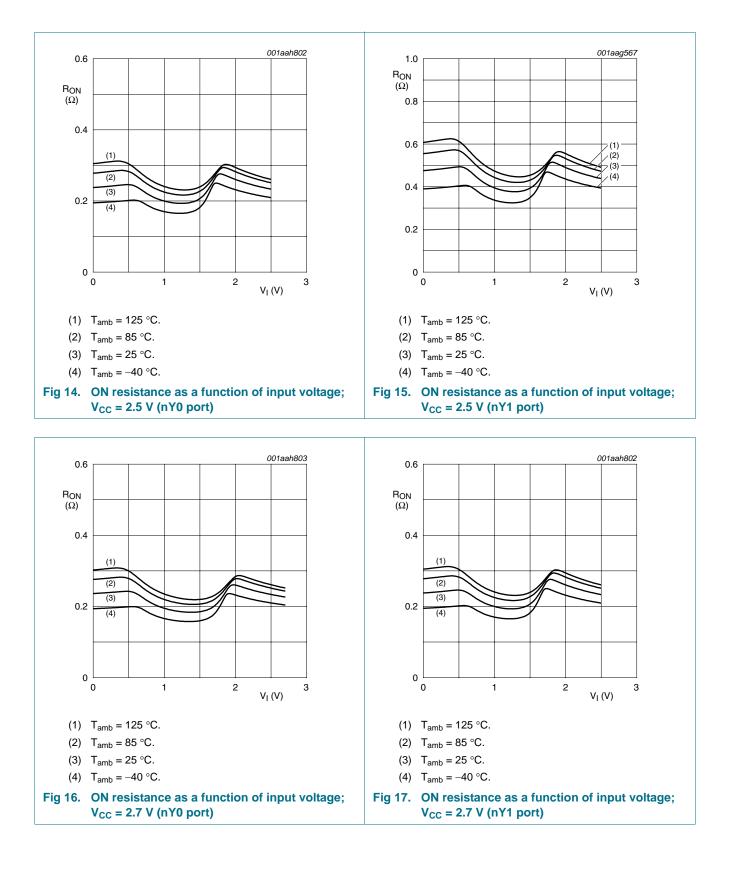




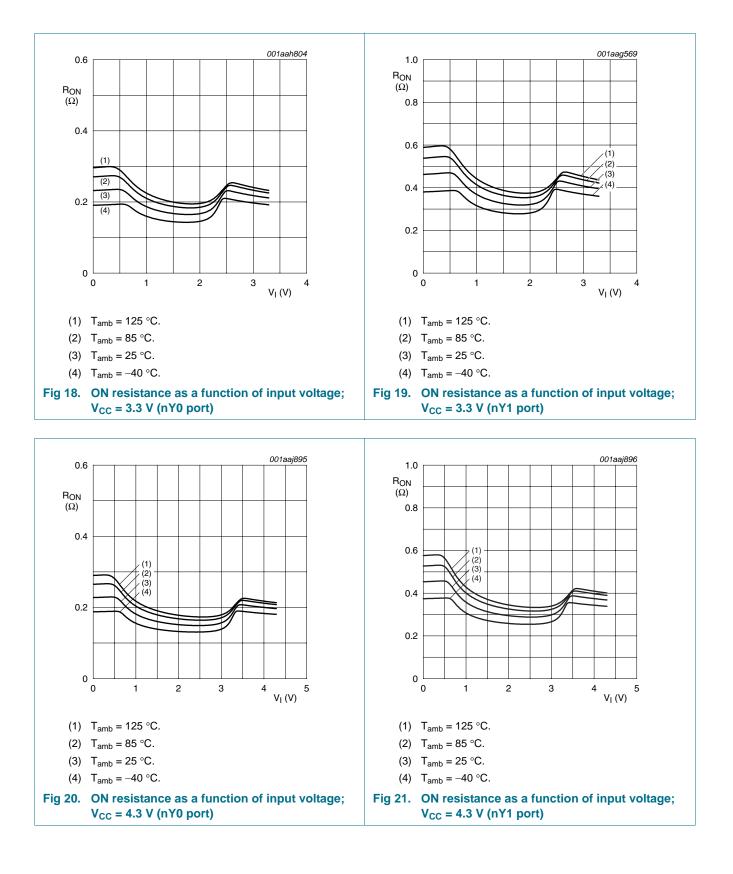
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12. Dynamic characteristics

Table 9. Dynamic characteristics

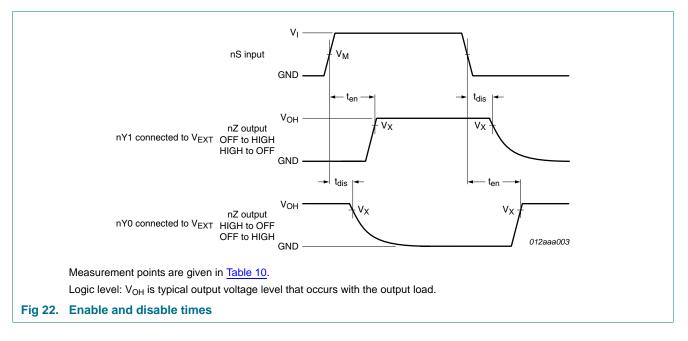
At recommended operating conditions; voltages are referenced to GND (ground = 0 V); for load circuit see Figure 24.

Symbol	Parameter	Conditions	Τ _ε	amb = 25	°C	T _{amb} =	–40 °C to	+125 °C	Unit
			Min	Typ <mark>[1]</mark>	Мах	Min	Max (85 °C)	Max (125 °C)	
t _{en}	enable time	nS to nZ or nYn; see <u>Figure 22</u>							
		V_{CC} = 1.4 V to 1.6 V	-	50	100	-	130	130	ns
		V_{CC} = 1.65 V to 1.95 V	-	35	80	-	85	95	ns
		V_{CC} = 2.3 V to 2.7 V	-	24	50	-	55	60	ns
		V_{CC} = 2.7 V to 3.6 V	-	20	45	-	50	55	ns
		V_{CC} = 3.6 V to 4.3 V	-	20	45	-	50	55	ns
t _{dis}	disable time	nS to nZ or nYn; see <u>Figure 22</u>							
		V_{CC} = 1.4 V to 1.6 V	-	30	70	-	80	90	ns
		V_{CC} = 1.65 V to 1.95 V	-	18	55	-	60	65	ns
		V_{CC} = 2.3 V to 2.7 V	-	11	25	-	30	35	ns
		V_{CC} = 2.7 V to 3.6 V	-	9	20	-	25	30	ns
		V_{CC} = 3.6 V to 4.3 V	-	9	20	-	25	30	ns
t _{b-m}	break-before-make	see Figure 23	l						
	time	V_{CC} = 1.4 V to 1.6 V	-	20	-	9	-	-	ns
		V_{CC} = 1.65 V to 1.95 V	-	19	-	7	-	-	ns
		V_{CC} = 2.3 V to 2.7 V	-	13	-	4	-	-	ns
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	-	10	-	2	-	-	ns
		$V_{CC} = 3.6 \text{ V to } 4.3 \text{ V}$	-	10	-	1	-	-	ns

[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 1.5 V, 1.8 V, 2.5 V, 3.3 V and 4.3 V respectively.

[2] Break-before-make guaranteed by design.

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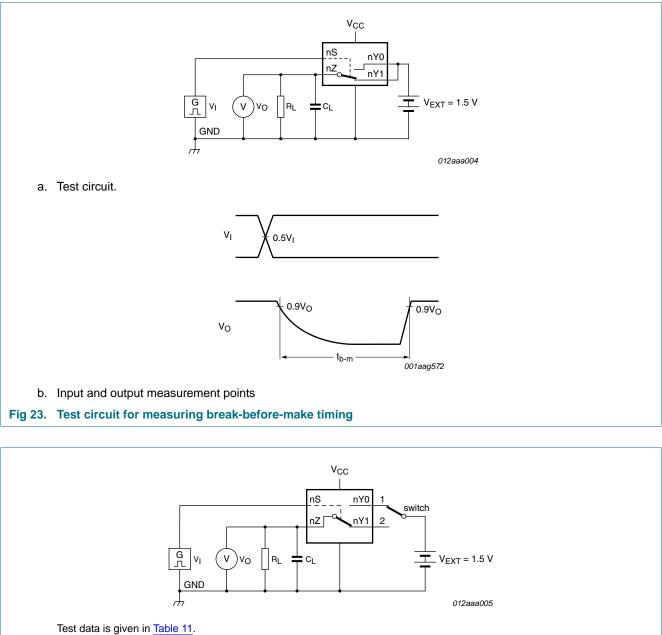
12.1 Waveform and test circuits

Table 10. Measurement points

Supply voltage	Input	Output
V _{CC}	V _M	V _X
1.4 V to 4.3 V	0.5V _{CC}	0.9V _{OH}

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Definitions test circuit:

R_L = Load resistance.

 C_L = Load capacitance including jig and probe capacitance.

V_{EXT} = External voltage for measuring switching times.

Fig 24. Load circuit for switching times

Table 11. Test data

Supply voltage	Input I		Load	
V _{cc}	VI	t _r , t _f	CL	RL
1.4 V to 4.3 V	V _{CC}	\leq 2.5 ns	35 pF	50 Ω

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12.2 Additional dynamic characteristics

Table 12. Additional dynamic characteristics

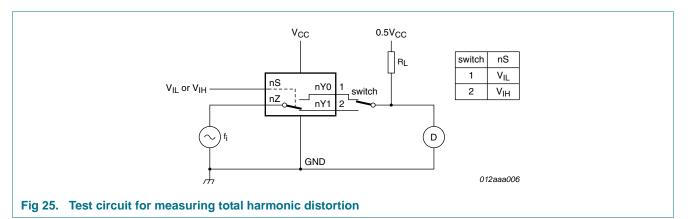
At recommended operating conditions; voltages are referenced to GND (ground = 0 V); $V_I = GND$ or V_{CC} (unless otherwise specified); $t_r = t_f \le 2.5$ ns.

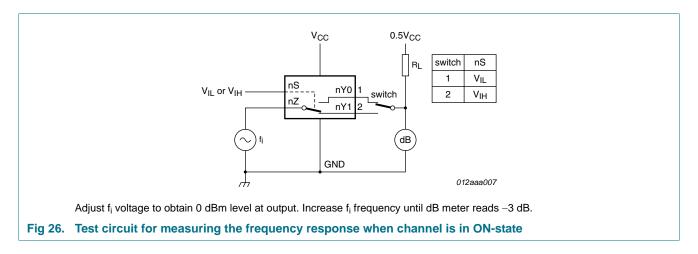
Symbol	Parameter	Conditions		Ta	_{mb} = 25 °C		Unit
				Min	Тур	Max	
THD	total harmonic	$f_i = 20$ Hz to 20 kHz; $R_L = 32 \Omega$; see Figure 25	[1]				
	distortion	V _{CC} = 1.4 V; V _I = 1 V (p-p)		-	0.06	-	%
		V _{CC} = 1.65 V; V _I = 1.2 V (p-p)		-	0.02	-	%
		V _{CC} = 2.3 V; V _I = 1.5 V (p-p)		-	0.02	-	%
		$V_{CC} = 2.7 \text{ V}; \text{ V}_{I} = 2 \text{ V} (p-p)$		-	0.02	-	%
		V _{CC} = 4.3 V; V _I = 2 V (p-p)		-	0.02	-	%
		$V_{CC} = 3.0 \text{ V}; \text{ V}_{I} = 1 \text{ V} (p-p); \text{ R}_{L} = 600 \Omega$		-	0.01	-	%
f _(-3dB)	-3 dB frequency	$R_L = 50 \Omega$; see <u>Figure 26</u>	<u>[1]</u>				
	response	port nY0; V_{CC} = 1.4 V to 4.3 V		-	15	-	MHz
		port nY1; V_{CC} = 1.4 V to 4.3 V		-	20	-	MHz
α_{iso}	isolation (OFF-state)	$f_i = 100 \text{ kHz}; R_L = 50 \Omega; \text{ see } \frac{\text{Figure 27}}{100 \text{ kHz}}$	<u>[1]</u>				
		$V_{CC} = 1.4 \text{ V} \text{ to } 4.3 \text{ V}$		-	-90	-	dB
V _{ct}	crosstalk voltage	between digital inputs and switch; $f_i = 1 \text{ MHz}$; $C_L = 50 \text{ pF}$; $R_L = 50 \Omega$; see Figure 28					
		$V_{CC} = 1.4 \text{ V to } 3.6 \text{ V}$		-	0.5	-	V
		$V_{CC} = 3.6 \text{ V to } 4.3 \text{ V}$		-	0.7	-	V
Xtalk	crosstalk	between switches; $f_i = 100 \text{ kHz}$; $R_L = 50 \Omega$; see <u>Figure 29</u>	<u>[1]</u>				
		$V_{CC} = 1.4 \text{ V to } 4.3 \text{ V}$		-	-90	-	dB
Q _{inj}	charge injection	$ f_i = 1 \text{ MHz; } C_L = 0.1 \text{ nF; } R_L = 1 \text{ M}\Omega; V_{gen} = 0 \text{ V; } \\ R_{gen} = 0 \Omega; \text{ see } \frac{\text{Figure } 30}{1000} $					
		$V_{CC} = 1.5 V$		-	10	-	рС
		V _{CC} = 1.8 V		-	14	-	рС
		$V_{CC} = 2.5 V$		-	21	-	рС
		$V_{CC} = 3.3 V$		-	30	-	рС
		$V_{CC} = 4.3 V$		-	50	-	рС

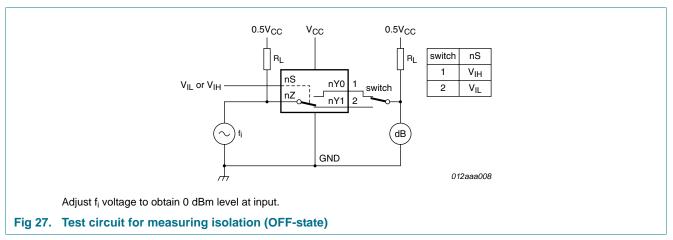
[1] f_i is biased at 0.5V_{CC}.

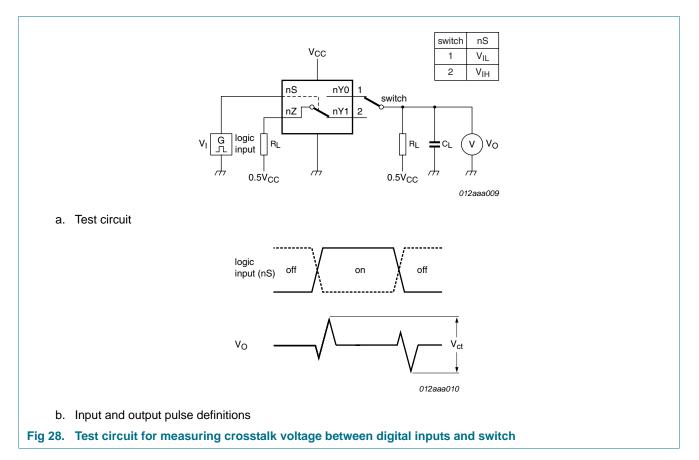
Dual low-ohmic single-pole double-throw analog switch

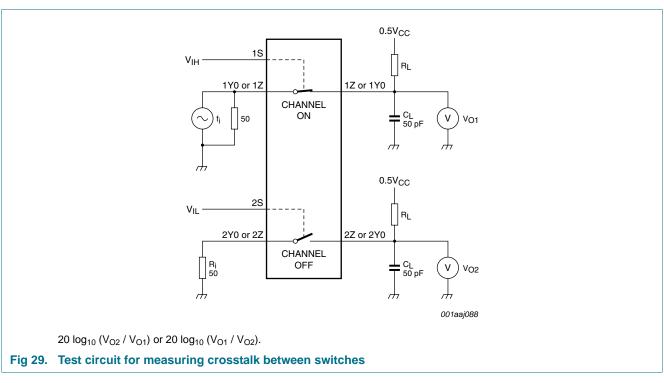
12.3 Test circuits



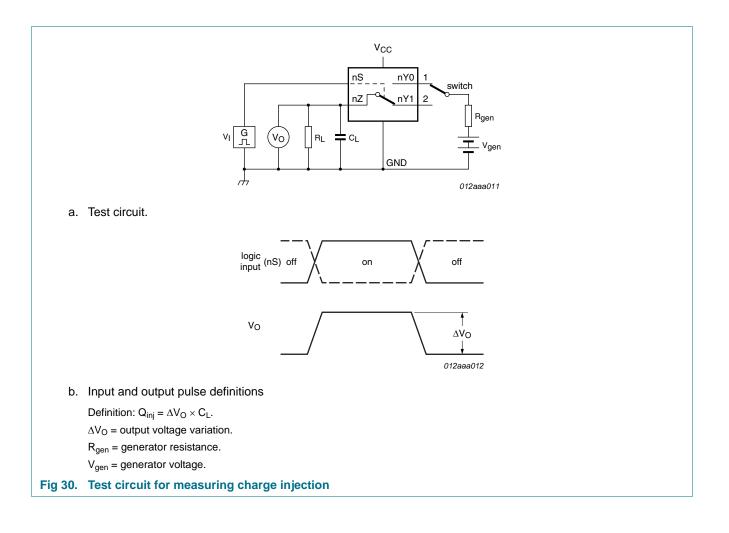








NX3L4684



NX3L4684

Dual low-ohmic single-pole double-throw analog switch

13. Package outline

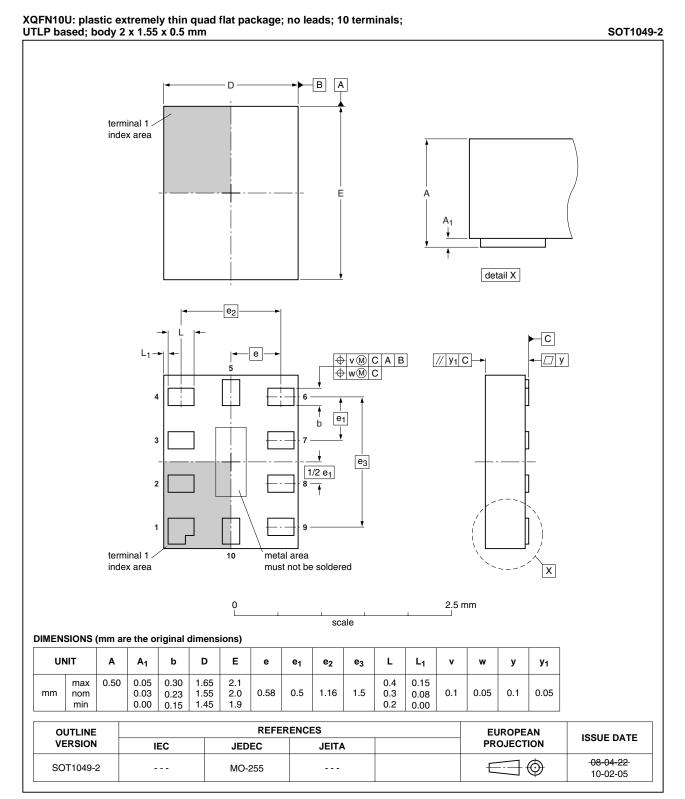
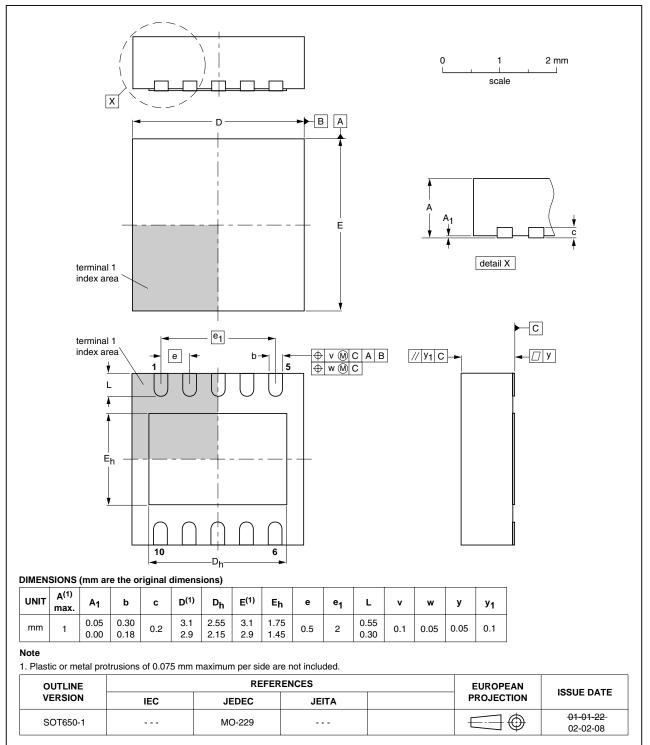


Fig 31. Package outline SOT1049-2 (XQFN10U)

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Dual low-ohmic single-pole double-throw analog switch



HVSON10: plastic thermal enhanced very thin small outline package; no leads; 10 terminals; body 3 x 3 x 0.85 mm

SOT650-1

Fig 32. Package outline SOT650-1 (HVSON10)

14. Abbreviations

Table 13. Abbreviations				
Acronym	Description			
CDM	Charged Device Model			
CMOS	Complementary Metal-Oxide Semiconductor			
ESD	ElectroStatic Discharge			
HBM	Human Body Model			
MM	Machine Model			
PDA	Personal Digital Assistant			

15. Revision history

Table 14. Revision history								
Document ID	Release date	Data sheet status	Change notice	Supersedes				
NX3L4684_4	20100324	Product data sheet	-	NX3L4684_3				
NX3L4684_3	20100209	Product data sheet	-	NX3L4684_2				
Modifications:	• <u>Table 8</u> : ON	resistance (flatness) for pins n	Y0 and nY1 changed a	at V _{CC} = 4.3 V.				
NX3L4684_2	20090401	Product data sheet	-	NX3L4684_1				
NX3L4684_1	20081127	Product data sheet	-	-				

16. Legal information

16.1 Data sheet status

Document status[1][2]	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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NX3L4684 4

Dual low-ohmic single-pole double-throw analog switch

17. Contact information

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NX3L4684

Dual low-ohmic single-pole double-throw analog switch

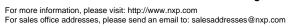
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